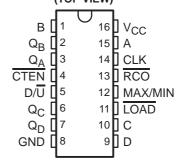
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- 2-V to 6-V V<sub>CC</sub> Operation ('HC190, 191)
- 4.5-V to 5.5-V V<sub>CC</sub> Operation ('HCT191)
- Wide Operating Temperature Range of -55°C to 125°C
- Synchronous Counting and Asynchronous Loading
- Two Outputs for n-Bit Cascading
- Look-Ahead Carry for High-Speed Counting
- Balanced Propagation Delays and Transition Times
- Standard Outputs Drive Up To 15 LS-TTL Loads
- Significant Power Reduction Compared to LS-TTL Logic ICs

CD54HC190, 191; CD54HCT191 . . . F PACKAGE CD74HC190 . . . E, NS, OR PW PACKAGE CD74HC191, CD74HCT191 . . . E OR M PACKAGE (TOP VIEW)



### description/ordering information

The CD54/74HC190 are asynchronously presettable BCD decade counters, whereas the CD54/74HC191 and CD54/74HCT191 are asynchronously presettable binary counters.

Presetting the counter to the number on preset data inputs (A–D) is accomplished by a low asynchronous parallel load  $(\overline{LOAD})$  input. Counting occurs when  $\overline{LOAD}$  is high, count enable  $(\overline{CTEN})$  is low, and the down/up  $(D/\overline{U})$  input is either high for down counting or low for up counting. The counter is decremented or incremented synchronously with the low-to-high transition of the clock.

### **ORDERING INFORMATION**

TA	PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING
			CD74HC190E	CD74HC190E
	PDIP – E	Tube of 25	CD74HC191E	CD74HC191E
			CD74HCT191E	CD74HCT191E
		Tube of 40	CD74HC191M	
	CO10 M	Reel of 2500	CD74HC191M96	HC191M
	SOIC - M	Reel of 250	CD74HC191MT	
5500 / 40500		Tube of 40	CD74HCT191M	HCT191M
–55°C to 125°C	SOP - NS	Reel of 2000	CD74HC190NSR	HC190M
		Tube of 90	CD74HC190PW	
	TSSOP - PW	Reel of 2000	CD74HC190PWR	HJ190
		Reel of 250	CD74HC190PWT	
			CD54HC190F3A	CD54HC190F3A
	CDIP – F	Tube of 25	CD54HC191F3A	CD54HC191F3A
			CD54HCT191F3A	CD54HCT191F3A

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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### description/ordering information (continued)

When an overflow or underflow of the counter occurs, the MAX/MIN output, which is low during counting, goes high and remains high for one clock cycle. This output can be used for look-ahead carry in high-speed cascading (see Figure 1). The MAX/MIN output also initiates the ripple clock (RCO) output, which normally is high, goes low, and remains low for the low-level portion of the clock pulse. These counters can be cascaded using RCO (see Figure 2).

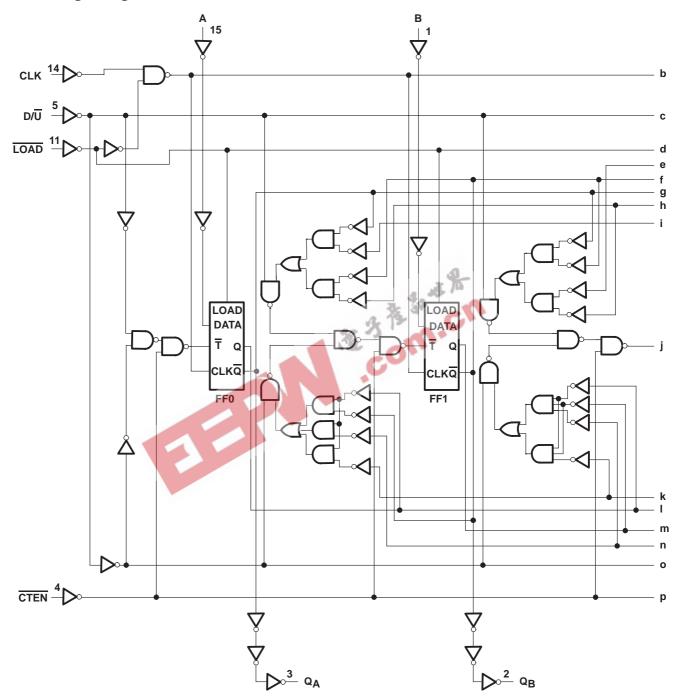
If a decade counter is preset to an illegal state or assumes an illegal state when power is applied, it returns to the normal sequence in one or two counts, as shown in the state diagrams (see Figure 3).

#### **FUNCTION TABLE**

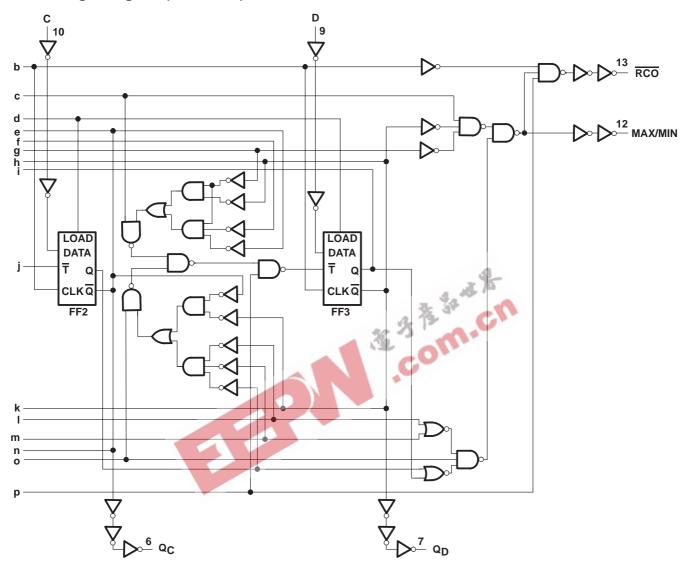
	INP	JTS		FUNCTION
LOAD	CTEN	D/U	CLK	FUNCTION
Н	L	L		Count up
Н	L	Н		Count down
L	Х	Х	Х	Asynchronous preset
Н	Н	Х	Х	No change
E				.com.c



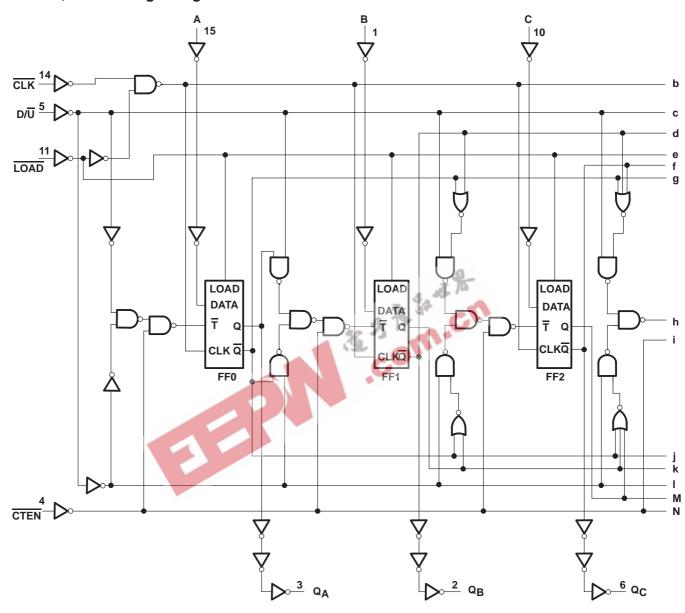
# 'HC190 logic diagram



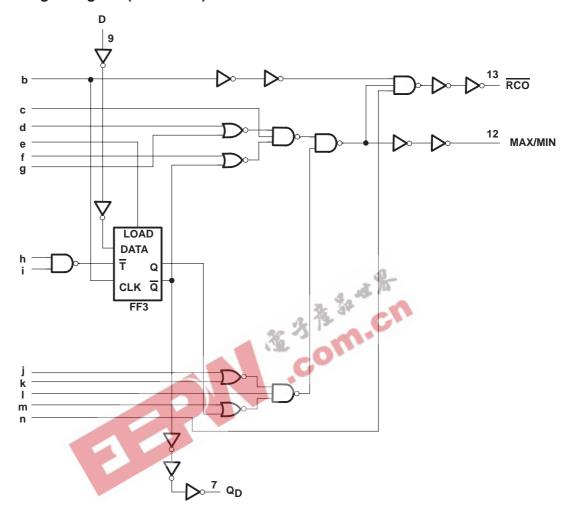
# 'HC190 logic diagram (continued)



# 'HC191, 'HCT191 logic diagram

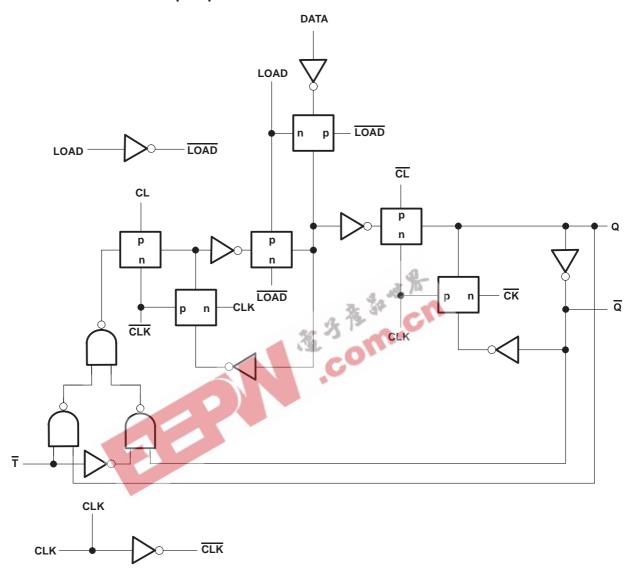


# 'HC191, 'HCT191 logic diagram (continued)





# 'HC190 and 'HC191/HCT191 flip-flop

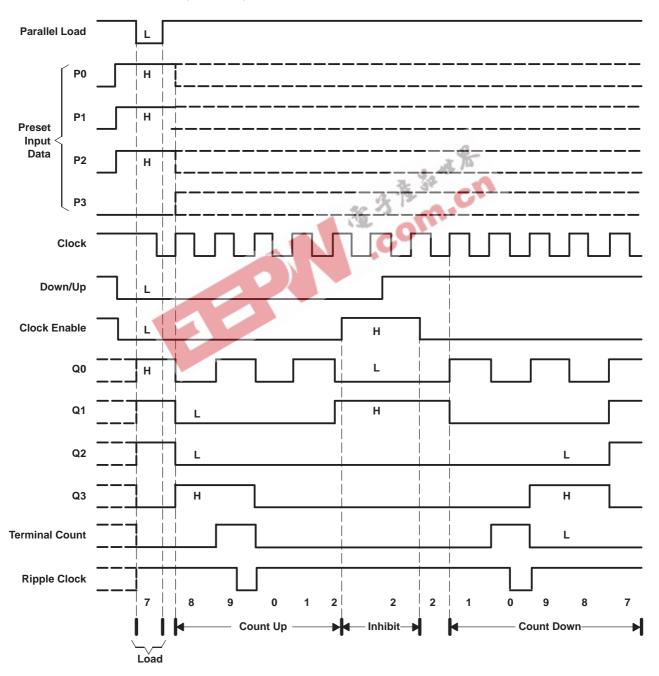


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### typical load, count, and inhibit sequence for 'HC190

The following sequence is illustrated below:

- 1. Load (preset) to BCD 7
- 2. Count up to 8, 9 (maximum), 0, 1, and 2
- 3. Inhibit
- 4. Count down to 1, 0 (minimum), 9, 8, and 7



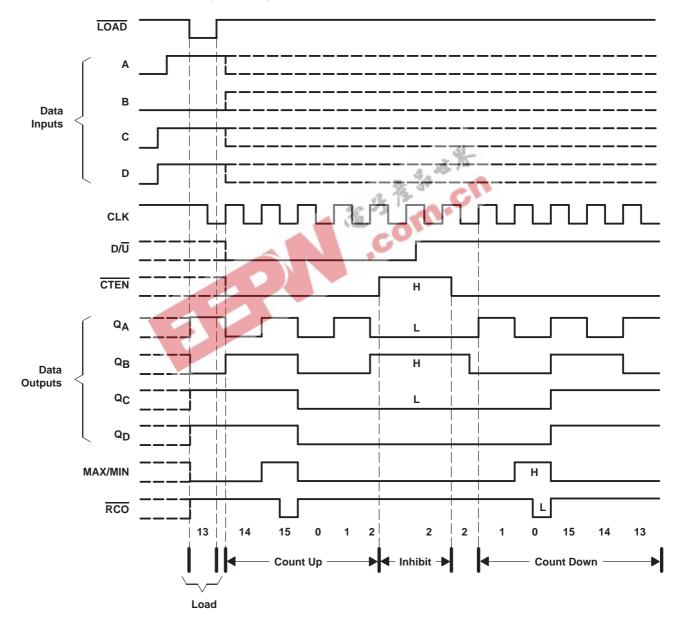


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## typical load, count, and inhibit sequence for 'HC191 and 'HCT191

The following sequence is illustrated below:

- 1. Load (preset) to binary 13
- 2. Count up to 14, 15 (maximum), 0, 1, and 2
- 3. Inhibit
- 4. Count down to 1, 0 (minimum), 15, 14, and 13



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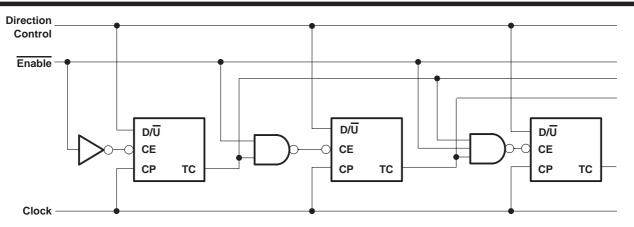


Figure 1. 'HC190 Synchronous n-Stage Counter With Parallel Gated Terminal Count

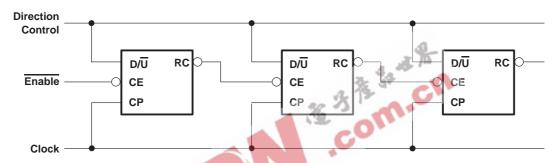
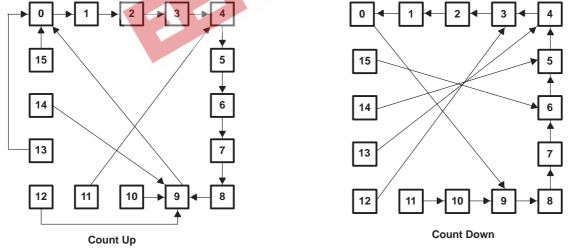


Figure 2. 'HC191, 'HCT191 Synchronous n-Stage Counter With Parallel Gated Terminal Count



NOTE: Illegal states in BCD counters corrected in one count

NOTE: Illegal states in BCD counters corrected in one or two counts

Figure 3. 'HC190 State Diagram



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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>		–0.5 V to 7 V
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0 or V <sub>I</sub> > V <sub>CC</sub> ) (se	e Note 1)	±20 mA
Output clamp current, IOK (VO < 0 or VO > VCC	e) (see Note 1)	±20 mA
Continuous output drain current per output, IO (	$V_O = 0$ to $V_{CC}$ )	±35 mA
Continuous output source or sink current per ou	itput, $I_O(V_O = 0 \text{ to } V_{CC})$	±25 mA
Continuous current through V <sub>CC</sub> or GND		±50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2):	E package	67°C/W
	M package	73°C/W
	NS package	64°C/W
	PW package	108°C/W
Storage temperature range, T <sub>stg</sub>		–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

# recommended operating conditions for 'HC190 and 'HC191 (see Note 3)

		33.3	T <sub>A</sub> = 25°C	T <sub>A</sub> = -55°C TO 125°C	T <sub>A</sub> = -40°C TO 85°C	UNIT
			MIN MAX	MIN MAX	MIN MAX	
VCC	Supply voltage		2 6	2 6	2 6	V
		V <sub>CC</sub> = 2 V	1.5	1.5	1.5	
$\vee_{IH}$	High-level input voltage	V <sub>CC</sub> = 4.5 V	3.15	3.15	3.15	V
		V <sub>CC</sub> = 6 V	4.2	4.2	4.2	
		∨ <sub>CC</sub> = 2 V	0.5	0.5	0.5	
VIL	Low-level input voltage	V <sub>CC</sub> = 4.5 V	1.35	1.35	1.35	V
		V <sub>CC</sub> = 6 V	1.8	1.8	1.8	
٧ <sub>I</sub>	Input voltage		0 V <sub>CC</sub>	0 V <sub>C</sub> C	0 V <sub>CC</sub>	V
VO	Output voltage		0 V <sub>CC</sub>	0 V <sub>C</sub> C	0 V <sub>CC</sub>	V
		V <sub>CC</sub> = 2 V	1000	1000	1000	_
t <sub>t</sub>	Input transition (rise and fall) time	V <sub>CC</sub> = 4.5 V	500	500	500	ns
		V <sub>CC</sub> = 6 V	400	400	400	

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

### recommended operating conditions for 'HCT191 (see Note 4)

		T <sub>A</sub> = 2	25°C	T <sub>A</sub> = -			T <sub>A</sub> = -40°C TO 85°C MIN MAX 4.5 5.5	
		MIN	MAX	MIN	MAX	MIN	MAX	
Vcc	Supply voltage	4.5	5.5	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		2		V
$V_{IL}$	Low-level input voltage		0.8		0.8		0.8	V
٧ <sub>I</sub>	Input voltage		VCC		VCC		VCC	V
٧o	Output voltage		VCC		VCC		VCC	V
t <sub>t</sub>	Input transition (rise and fall) time		500		500		500	ns

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

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### 'HC190, 'HC191

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST C	ONDITIONS	Vcc	T <sub>A</sub> =	25°C	T <sub>A</sub> = -		T <sub>A</sub> = -		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
			2 V	1.9		1.9		1.9		
		$I_{OH} = -20  \mu A$	4.5 V	4.4		4.4		4.4		
Voн	$V_I = V_{IH} \text{ or } V_{IL}$		6 V	5.9		5.9		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98		3.7		3.84		
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48		5.2		5.34		
			2 V		0.1		0.1		0.1	
		$I_{OL} = 20 \mu A$	4.5 V		0.1		0.1		0.1	
VOL	$V_I = V_{IH} \text{ or } V_{IL}$		6 V		0.1		0.1		0.1	V
		$I_{OL} = 4 \text{ mA}$	4.5 V		0.26		0.4		0.33	
		$I_{OL} = 5.2 \text{ mA}$	6 V		0.26		0.4		0.33	
lj	$V_I = V_{CC}$ or 0		6 V		±0.1		±1		±1	μΑ
<sup>I</sup> cc	$V_I = V_{CC}$ or 0,	I <sub>O</sub> = 0	6 V		8		160		80	μΑ
Ci				2. 答	10	37	10		10	pF

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CON	TEST CONDITIONS		T,	λ = 25°C	;	T <sub>A</sub> = -		T <sub>A</sub> = -		UNIT
			VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
	V VV	$I_{OH} = -20  \mu A$	457	4.4			4.4		4.4		.,
VOH	VI = VIH or VIL	$I_{OH} = -4 \text{ mA}$	4.5 V	3.98			3.7		3.84		V
.,	., ., .,	Ι <sub>ΟL</sub> = 20 μΑ	4.5.1/			0.1		0.1		0.1	.,
V <sub>OL</sub>	$V_I = V_{IH}$ or $V_{IL}$	I <sub>OL</sub> = 4 mA	4.5 V			0.26		0.4		0.33	V
Ι <sub>Ι</sub>	$V_I = V_{CC}$ to GND		5.5 V			±0.1		±1		±1	μΑ
Icc	$V_I = V_{CC}$ or 0,	I <sub>O</sub> = 0	5.5 V			8		160		80	μΑ
∆I <sub>CC</sub> †	One input at V <sub>CC</sub> – Other inputs at 0 or	2.1 V, VCC	4.5 V to 5.5 V		100	360		490		450	μΑ
Ci						10		10		10	pF

<sup>†</sup> Additional quiescent supply current per input pin, TTL inputs high, 1 unit load

### **HCT INPUT LOADING TABLE**

INPUTS	UNIT LOADS
A-D	0.4
CLK	1.5
LOAD	1.5
D/ <del>U</del>	1.2
CTEN	1.5

Unit load is  $\Delta I_{CC}$  limit specified in electrical characteristics table, (e.g., 360  $\mu$ A max at 25°C).



# 'HC190, 'HC191 timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 4)

			VCC	T <sub>A</sub> = 3	25°C	T <sub>A</sub> = -	-55°C 25°C	T <sub>A</sub> = -	-40°C 5°C	UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
			2 V		6		4		5	
fclock	Clock frequency†		4.5 V		30		20		25	MHz
			6 V		35		23		29	
			2 V	80		120		100		
		LOAD low	4.5 V	16		24		20		
	Pulse duration		6 V	14		20		17		20
t <sub>W</sub>	Pulse duration		2 V	100		150		125		ns
		CLK high or low	4.5 V	20		30		25		
			6 V	17		26		21		
			2 V	60		90		75		
		Data before LOAD↑	4.5 V	12		18		15		
			6 V	10	- %	15		13		
			2 V	60	10- /11	90		75		
t <sub>su</sub>	Setup time	CTEN before CLK↑	4.5 V	12		18		15		ns
		9	6 V	10		15		13		
		1	2 V	90	*	135		115		
		D/U before CLK↑	4.5 V	18		27		23		
			6 V	15		23		20		
			2 V	2		2		2		
		Data before LOAD↑	4.5 V	2		2		2		
			6 V	2		2		2		
			2 V	2		2		2		
th	Hold time	CTEN before CLK↑	4.5 V	2		2		2		ns
			6 V	2		2		2		
			2 V	0		0		0		
		D/ <del>U</del> before CLK↑	4.5 V	0		0		0		
			6 V	0		0		0		
			2 V	60		90		75		
trec	Recovery time	LOAD inactive before CLK↑	4.5 V	12		18		15		ns
	•		6 V	10		15		13		

<sup>†</sup> Applies to noncascaded operation only. With cascaded counters, clock-to-terminal count propagation delays, CTEN-to-clock setup times, and CTEN-to-clock hold times determine maximum clock frequency. For example, with these HC devices:

$$f_{\text{max}}(\text{CLK}) = \frac{1}{\text{CLK-to-MAX/MIN propagation delay} + \overline{\text{CTEN}}\text{-to-CLK setup time} + \overline{\text{CTEN}}\text{-to-CLK hold time}} = \frac{1}{42 + 12 + 2} \approx 18 \text{ MHz}$$

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'HC190, 'HC191

# switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 4)

PARAMETER	FROM	TO (OUTPUT)	LOAD CAPACITANCE	Vcc	T,	A = 25°(		T <sub>A</sub> = -	-55°C 25°C	T <sub>A</sub> = -	-40°C 5°C	UNIT
	(INPUT)	(001701)	CAPACITANCE		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
				2 V	6			4		5		
fmax				4.5 V	30			20		25		MHz
				6 V	35			23		29		
				2 V			195		295		245	
	LOAD	Q	C <sub>L</sub> = 50 pF	4.5 V			39		59		49	
	LOAD			6 V			33		50		42	
			C <sub>L</sub> = 15 pF	5 V		16						
				2 V			175		265		220	
	A, B, C,	Q	C <sub>L</sub> = 50 pF	4.5 V			35		53		44	
	or D	Q		6 V			30	*	45		37	
			C <sub>L</sub> = 15 pF	5 V		14	400					
				2 V		4 19	170	27	255		215	
	CLK	Q	C <sub>L</sub> = 50 pF	4.5 V	36	2)	34		51		43	
	CLN	l Q		6 V	V.SL	_0	29		43		37	
			C <sub>L</sub> = 15 pF	5 V		14						
				2 V			125		190		155	
	CLK	RCO	C <sub>L</sub> = 50 pF	4.5 V			25		38		31	
	CLN	KCO		6 V			21		32		26	
			C <sub>L</sub> = 15 pF	5 V		10						ns
<sup>t</sup> pd				2 V			210		315		265	115
	CLK	MAX/MIN	C <sub>L</sub> = 50 pF	4.5 V			42		63		53	
	CLN	IVIAA/IVIIIV		6 V			36		54		45	
			C <sub>L</sub> = 15 pF	5 V		18						
				2 V			150		225		190	
	D/ <del>U</del>	RCO	C <sub>L</sub> = 50 pF	4.5 V			30		45		38	
	D/0	RCO		6 V			26		38		33	
			C <sub>L</sub> = 15 pF	5 V		12						
				2 V			165		250		205	
	D/ <del>U</del>	MAX/MIN	C <sub>L</sub> = 50 pF	4.5 V			33		50		41	
	D/0	IVIAA/IVIIIN		6 V			28		43		35	
			C <sub>L</sub> = 15 pF	5 V		13						
				2 V			125		190		155	
	CTEN	RCO	C <sub>L</sub> = 50 pF	4.5 V			25		38		31	
	CIEN	, KCO		6 V			21		32		26	
			C <sub>L</sub> = 15 pF	5 V		10						
				2 V			75		110		95	
t <sub>t</sub>		Any	C <sub>L</sub> = 50 pF	4.5 V			15		22		19	ns
				6 V			13		19		16	



### 'HCT191

timing requirements over recommended operating free-air temperature range  $V_{CC}$  = 4.5 V (unless otherwise noted) (see Figure 5)

			T <sub>A</sub> = 3	25°C	T <sub>A</sub> = -		T <sub>A</sub> = -		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency			30		20		25	MHz
	Pode a desertion	LOAD low	16		24		20		
t <sub>W</sub>	Pulse duration	CLK high or low	20		30		25		ns
		Data before LOAD↑	12		18		15		
t <sub>su</sub>	Setup time	CTEN before CLK↑	12		18		15		ns
		D/U before CLK↑	18		27		23		
		Data before LOAD↑	2		2		2		
th	Hold time	CTEN before CLK↑	2		2		2		ns
		D/U before CLK↑	0	- 0	0		0		
t <sub>rec</sub>	Recovery time	LOAD inactive before CLK↑	12	3 15	18		15		ns

'HCT191

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 5)

PARAMETER	FROM	TO (OUTPUT)	LOAD CAPACITANCE	Vcc	т,	դ = 25°C	;	T <sub>A</sub> = -		T <sub>A</sub> = -		UNIT
	(INPUT)	(OUIPUI)	CAPACHANCE		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>				4.5 V	30			20		25		MHz
	LOAD	Q	C <sub>L</sub> = 50 pF	4.5 V			40		60		50	
	LOAD	Q	C <sub>L</sub> = 15 pF	5 V		17						
	A, B, C,	Q	$C_L = 50 pF$	4.5 V			38		57		48	
	or D	Q	$C_L = 15  pF$	5 V		16						
	CLK	RCO	$C_{L} = 50 \text{ pF}$	4.5 V			35		53		44	
	CLK	RCO	C <sub>L</sub> = 15 pF	5 V		14						
	CLK	Q	$C_{L} = 50 \text{ pF}$	4.5 V			27		41		34	
	CLK	Q	C <sub>L</sub> = 15 pF	5 V		11						ns
<sup>t</sup> pd	CLK	MAX/MIN	C <sub>L</sub> = 50 pF	4.5 V			42		63		53	115
	CLK	IVIAA/IVIIIN	C <sub>L</sub> = 15 pF	5 V		18						
	D/ <del>U</del>	RCO	$C_{L} = 50 \text{ pF}$	4.5 V			30		45		38	
	D/U	RCO	C <sub>L</sub> = 15 pF	5 V		12						
	D/ <del>U</del>	MAX/MIN	C <sub>L</sub> = 50 pF	4.5 V			38		57		48	
	D/U	IVIAA/IVIIIN	C <sub>L</sub> = 15 pF	5 V		16						
	CTEN	RCO	$C_{L} = 50 \text{ pF}$	4.5 V			27		41		34	
	CIEN	RCO	C <sub>L</sub> = 15 pF	5 V		11						
t <sub>t</sub>		Any	$C_{L} = 50 \text{ pF}$	4.5 V			15		22		19	ns

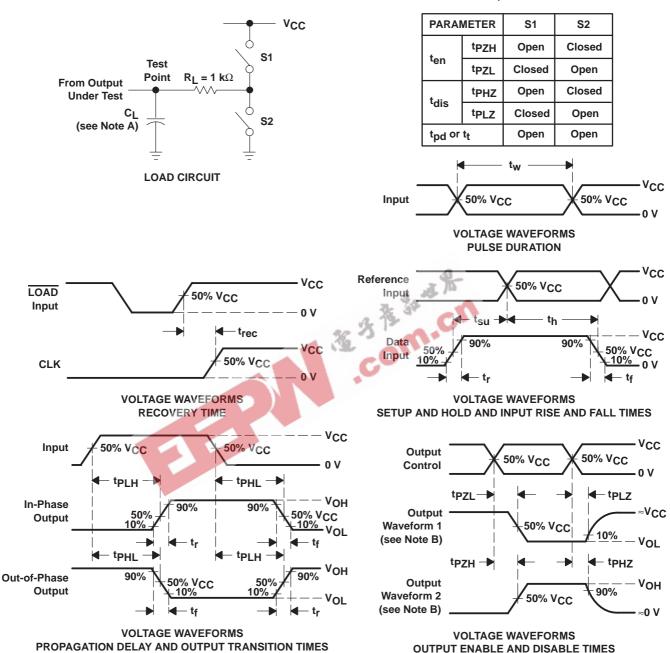
# operating characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

PARAMETER				
		'HC190	59	
C <sub>pd</sub>	Power dissipation capacitance	'HC191	55	pF
		'HCT191	68	



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### PARAMETER MEASUREMENT INFORMATION - 'HC190, 'HC191

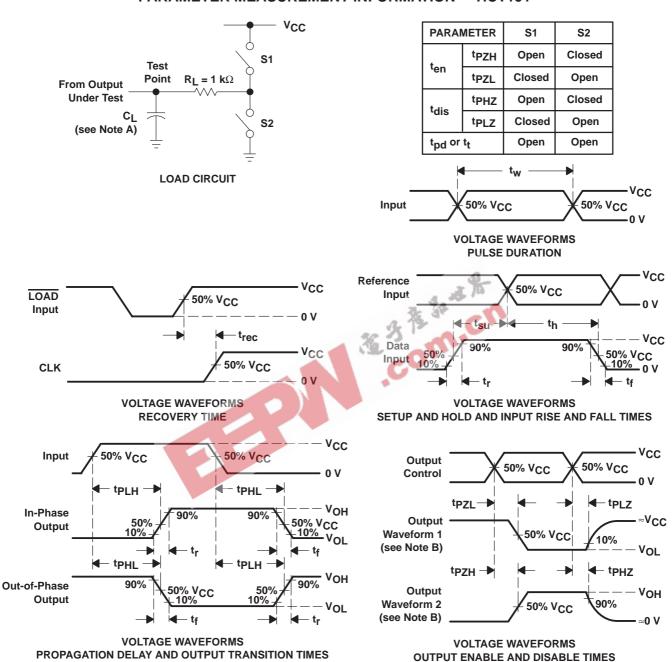


- NOTES: A. C<sub>L</sub> includes probe and test-fixture capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_Q = 50 \ \Omega$ ,  $t_f = 6 \ ns$ ,  $t_f = 6 \ ns$ .
  - D. For clock inputs, f<sub>max</sub> is measured with the input duty cycle at 50%.
  - E. The outputs are measured one at a time with one input transition per measurement.
  - F. tpLZ and tpHZ are the same as tdis.
  - G.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - H. tpLH and tpHL are the same as tpd.

Figure 4. Load Circuit and Voltage Waveforms



### PARAMETER MEASUREMENT INFORMATION - 'HCT191



- NOTES: A. C<sub>I</sub> includes probe and test-fixture capacitance.
  - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_r = 6$  ns,  $t_f = 6$  ns.
  - For clock inputs, f<sub>max</sub> is measured with the input duty cycle at 50%.
  - The outputs are measured one at a time with one input transition per measurement.
  - F. tpLz and tpHz are the same as tdis.
  - G. tpzl and tpzH are the same as ten.
  - H. tpLH and tpHL are the same as tpd.

Figure 5. Load Circuit and Voltage Waveforms







6-Dec-2006

### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3</sup>
5962-8867101EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8994601EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
CD54HC190F3A	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
CD54HC191F3A	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
CD54HCT191F3A	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
CD74HC190E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HC190EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HC190NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
CD74HC190NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
CD74HC190PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
CD74HC190PWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
CD74HC190PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
CD74HC190PWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
CD74HC190PWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
CD74HC190PWTE4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
CD74HC191E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HC191EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HC191M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
CD74HC191M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
CD74HC191M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
CD74HC191ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
CD74HC191MT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
CD74HC191MTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
CD74HCT191E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HCT191EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HCT191M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
CD74HCT191ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI



### PACKAGE OPTION ADDENDUM

6-Dec-2006

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <a href="http://www.ti.com/productcontent">http://www.ti.com/productcontent</a> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

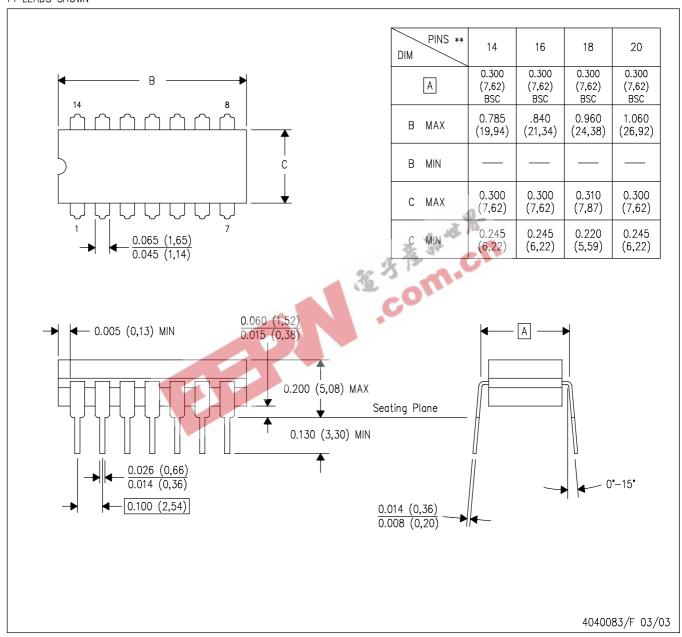
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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14 LEADS SHOWN

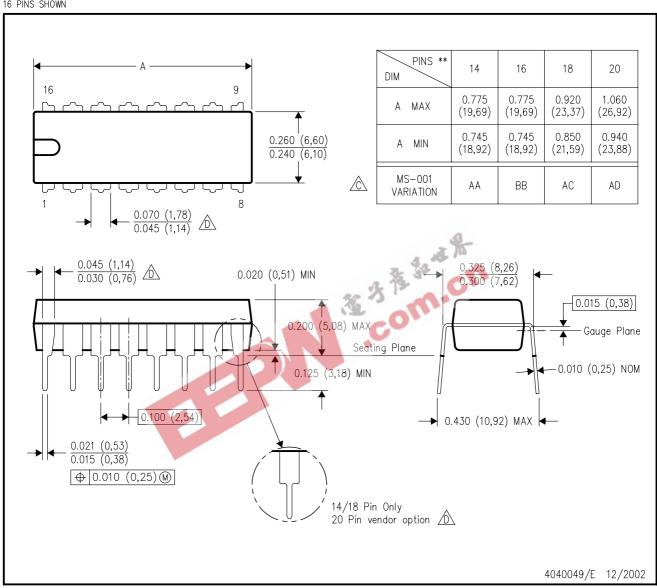


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- $E. \quad \text{Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.} \\$

# N (R-PDIP-T\*\*)

# PLASTIC DUAL-IN-LINE PACKAGE

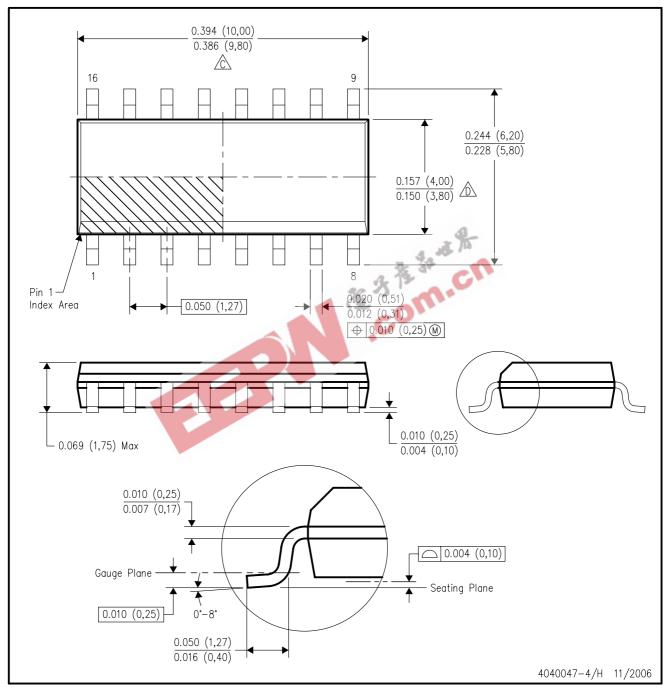
16 PINS SHOWN



- All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.

# D (R-PDSO-G16)

# PLASTIC SMALL-OUTLINE PACKAGE



- All linear dimensions are in inches (millimeters).
- A. All linear dimensions are in inches (millimeters).
  B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

  E. Reference JEDEC MS-012 variation AC.

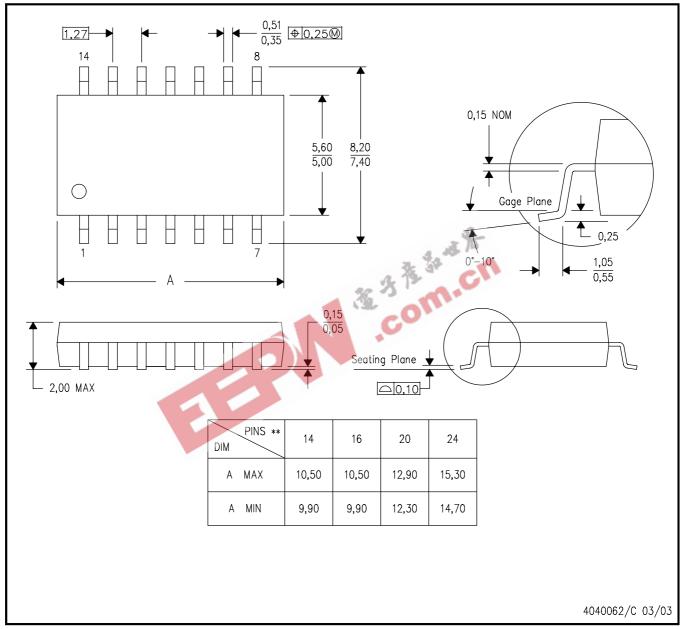


### **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

### 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



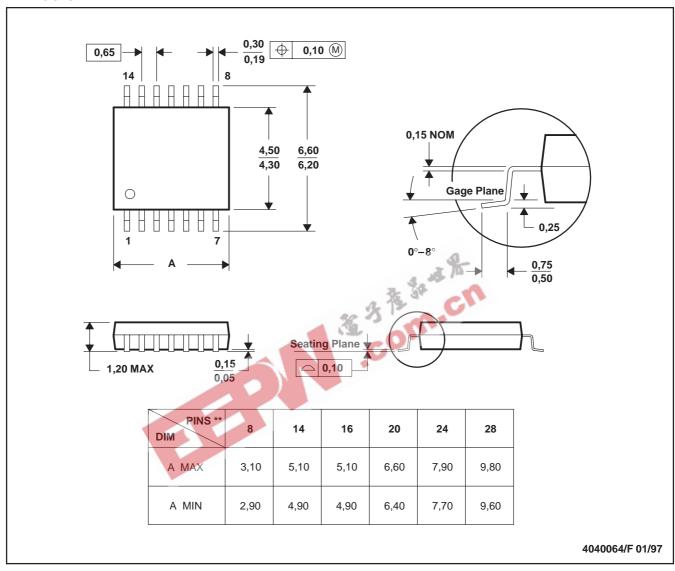
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



### PW (R-PDSO-G\*\*)

### PLASTIC SMALL-OUTLINE PACKAGE

### 14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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